

**REMARKS**

The present invention relates to an adhesive label comprising a circuit substrate, electronic component formed on at least one surface of the circuit substrate, and an adhesive layer on the electronic component; the adhesive layer can be applied to an article.

In the present Amendment, claim 1 has been amended to recite that the adhesive layer is in direct contact with the electronic components. This amendment is supported by the specification, for example, in Figs. 1 and 2. Claim 6 has been amended to recite that a surface layer is formed directly on the other of said separately formed electronic components. This amendment is supported by the specification, for example, at page 6, 1st full paragraph and Figure 2. Claim 3 has previously been canceled. No new matter has been added and entry of the Amendment is respectfully requested. Upon entry of the Amendment, claims 1-2 and 4-7 will be all the claims pending in the application.

In the Office Action dated October 19, 2004, claims 1, 2, 4, 5 and 7 were rejected under 35 U.S.C. § 102(a) as allegedly being anticipated by Tanimura et al (U.S. Pat. No. 6,065,701). Further, claim 6 was rejected under 35 U.S.C. § 103(a) as allegedly being unpatentable over Tanimura et al in view of "Applicants' admissions."

Applicants respectfully submit that the present claims are not anticipated or rendered obvious by Tanimura et al, alone or further in view of "Applicants' admissions" for at least the following reasons.

Present claim 1 recites that “the adhesive layer is in direct contact with the electronic components.” On the other hand, the adhesive layer 17 in Fig. 2 of Tanimura et al does not come into direct contact with the electronic components. Further, Tanimura et al does not suggest that the adhesive layer is in direct contact with the electronic components. Accordingly, Applicants respectfully submit that the present claims are novel and patentable over Tanimura et al, alone or in view of “Applicants’ admissions.”

Further, present claims 5 and 7 each recites a surface layer that is on the *reverse* side to a surface carrying the electronic element. However, in Tanimura et al, the polyimide substrate 16 carries the electronic element, and the coated paper layer 12 faces, or is on the *same* side as, the surface of the polyimide substrate where the electronic element is located (Fig. 2). Accordingly, Applicants respectfully submit that claims 5 and 7 are novel and patentable over Tanimura et al for this reason separately.

Still further, assuming that there may be motivation to combine the cited references, that is, antenna wiring 30 and IC 20 in Fig. 2 of Tanimura et al are located on two sides of the polyimide substrate 16, the adhesive layer 17 comes into direct contact with antenna wiring 30 (or IC 20) and the adhesive layer 15 comes into direct contact with IC 20 (or antenna wiring 30). In other words, the coated layer 12 is not in direct contact with either antenna wiring 30 or IC 20.


On the other hand, in the present invention, the substrate 1 carries the contact-less data carrier element containing electronic components. The surface layer 4 is in direct contact with one surface of the substrate 1, and the adhesive layer 7 is in direct contact with

the other surface of the substrate 1 (Fig. 2). Thus, when the electronic components are separately formed on each surface of the substrate as recited in present claim 6, both the surface layer 4 and the adhesive layer 7 are in direct contact with part of the contact-less data carrier element. Accordingly, Applicants respectfully submit that claim 6 is novel and patentable over Tanimura et al for this reason separately.

In view of the above, reconsideration and allowance of claims 1-2 and 4-7 are now believed to be in order, and such actions are hereby solicited. If any points remain in issue which the Examiner feels may be best resolved through a personal or telephone interview, the Examiner is kindly requested to contact the undersigned at the local Washington D.C. telephone number listed below.

The USPTO is directed and authorized to charge all required fees, except for the Issue Fee and the Publication Fee, to Deposit Account No. 19-4880. Please also credit any overpayments to said Deposit Account.

Respectfully submitted,



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WASHINGTON OFFICE

**23373**

CUSTOMER NUMBER

Date: April 15, 2005